

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Thomas H. Ivers et al.

Serial No.: 09/231,618

Art Unit: 2823

Filed: January 14, 1999

Examiner: Collins, D.

For: Method for Improving
Adhesion to Copper

Atty Docket: FI9-98-172

SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

Sir:

Applicants submit herewith 1 sheet of formal drawings of Figs. 1-3.

Respectfully submitted,



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